PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Keiji JITSUKAWA	09/07/2007
Noriyoshi ISHII	09/07/2007
Kiyoshi OMORI	09/07/2007
Katsunori TAKAHASHI	09/07/2007
Tomoyasu TAKAOKA	09/07/2007
Yuji SUZUKI	09/07/2007
Shigeru TAMURA	09/07/2007
Satoshi MUTO	09/07/2007

RECEIVING PARTY DATA

Name:	Sony NEC Optiarc Inc.
Street Address:	11-1, Osaki 1-chome, Shinagawa-ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11836295

OP $40.00 11836295

CORRESPONDENCE DATA

Fax Number: (703)413-2220
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: (703) 413-3000
Email: vbojanic@oblon.com
Correspondent Name: Oblon, Spivak, et al.
Address Line 1: 1940 Duke Street
Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	311725US8X

NAME OF SUBMITTER:	Vesna Bojanic

Total Attachments: 3
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Docket Number: 311725US8X

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

DISK DRIVE DEVICE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony NEC Optiarc Inc. with offices at 11-1, Osaki 1-chome, Shinagawa-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/836,295
Filing Date: AUGUST 9, 2007

This assignment executed on the dates indicated below.

Keiji JITSUKAWA
Name of first or sole inventor — Execution date of U.S. Patent Application

Chiba, Japan
Residence of first or sole inventor

KEIJI JITSUKAWA — 07/Sep/2007
Signature of first or sole inventor — Date of this assignment

Noriyoshi ISHII
Name of second inventor
Execution date of U.S. Patent Application

Chiba, Japan
Residence of second inventor

Noriyoshi Ishii
Signature of second inventor
Sep. 7. 2007
Date of this assignment

Kiyoshi OMORI
Name of third inventor
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of third inventor

Kiyoshi Omori
Signature of third inventor
September 7, 2007
Date of this assignment

Katsunori TAKAHASHI
Name of fourth inventor
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of fourth inventor

Katsunori Takahashi
Signature of fourth inventor
Sep. 7. 2007
Date of this assignment

Tomoyasu TAKAOKA
Name of fifth inventor
Execution date of U.S. Patent Application

Saitama, Japan
Residence of fifth inventor

Takaoka Tomoyasu
Signature of fifth inventor
Sep. 7. 2007
Date of this assignment

Yuji SUZUKI
Name of sixth inventor
Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of sixth inventor

Y. Suzuki
Signature of sixth inventor
07/Sep/'07
Date of this assignment

Shigeru TAMURA
Name of seventh inventor
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of seventh inventor

S. Tamura
Signature of seventh inventor
07/Sep/2007
Date of this assignment

Satoshi MUTO
Name of eighth inventor Execution date of U.S. Patent Application

Chiba, Japan
Residence of eighth inventor

Satoshi Mutou 07 / Sep / 2007
Signature of eighth inventor Date of this assignment

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